

In the Specification:

Please amend the specification where indicated.

At page 1, lines 5-15:

This Application claims priority for common subject matter to U.S. Provisional Patent Application Serial No. 60/198,365 (AMDA.475P1/TT3991), filed on April 19, 2000 and entitled "Semiconductor Analysis Arrangement and Method Therefor," which is fully incorporated herein by reference. This application is further related to U.S. Patent Application Serial No. 09/838,671 (AMDA.517PA/TT3991P2), entitled "Semiconductor Analysis Arrangement and Method Therefor"; to U.S. Patent Application Serial No. 09/838,667 (AMDA.518PA/TT3991P3), entitled "Semiconductor Analysis Using Thermal Control"; and to U.S. Patent Application Serial No. 09/838,672 (AMDA.519PA/TT3991P4), entitled "Semiconductor Analysis Arrangement and Method Therefor," all of which are filed concurrently herewith.

At page 5, line 20 – page 6 line 13:

FIG. 1 shows a system 100 for analyzing a semiconductor die 102, according to an example embodiment of the present invention. The system includes a test head 105 adapted to hold the die 102 and to dock with a chamber 110 via a coupling arrangement 140. Once the test head is docked with the chamber, one or more perturbation devices 101, including a light source 106 and other devices, such as a FIB, laser, sonic, microwave, electron beam or ion beam device, is used to analyze the die. Operation control data, such as chamber condition, die response, and other data, is provided to a controller 115. The controller is further adapted to receive response data from the die, such as electrical data obtained from die outputs. The perturbation devices 101 are also optionally coupled to the controller 115, and the controller can be adapted to control and receive feedback from the devices 101. A monitor 120 is coupled to the controller 115 and adapted to display information such as response data, control data. In one particular implementation, the monitor is used as part of an interface for controlling the system 100. For more information regarding the use of a controller in connection with the present invention, reference may be made to U.S. Patent Application Serial No. _____

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09/838,672 (AMDA.519PA/TT3991P4), entitled "Semiconductor Analysis Arrangement and Method Therefor."

At page 7, lines 6-19:

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In another example embodiment of the present invention, a photodiode 220 is coupled to the fiber optic cable 210, is communicatively coupled to a controller 280 via communications link 281 and is adapted to detect light leakage from the cable. In response to an amount of light that might leak from the cable, the photodiode generates a signal that is sent to the controller 280. The controller receives the signal and uses it for controlling the analysis of the semiconductor die 275. By detecting light leaking from the fiber optic cable, the corresponding response from the die can be more accurately analyzed because the amount of light incident upon the die can be detected and/or estimated. Any corresponding change in the stimulation or response to the amount of light is accounted for using the detected leakage. In addition, undesirable leakage levels can be avoided. For more information regarding the detection of light leakage, reference may be made to U.S. Patent Application Serial No. 09/838,671 (AMDA.517PA/TT3991P2), entitled "Semiconductor Analysis Arrangement and Method Therefor."